

OPERATING PROCEDURE CVC 601 DC Sputter Deposition Changing 3-Inch Target

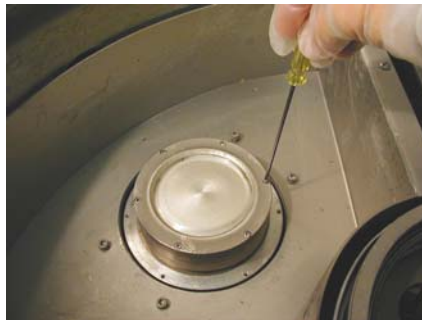
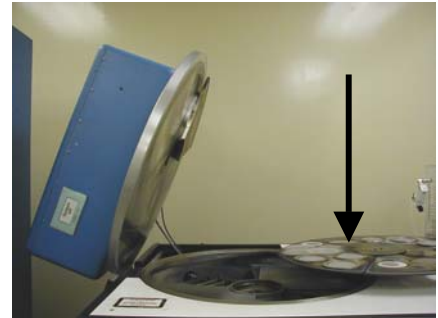
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Follow Operating Procedures for Venting.

1. Remove two inserts from Rotostrate platen.
2. Use the two openings for hand holds. Lift platen and set aside.
3. Parts needed for target change:



- Screwdriver
- Cathode shield
- Spacer rings
- Silver paste
- Target ring
- Ohm meter



4. Remove six screws located at base of cathode shield.
5. Lift off the cathode shield and set it aside.
6. Remove six screws in the target ring. Remove the target ring. Lift out target and place in case. Store target in dry box.

7. Apply thin film of silver paste to backside of desired target.
8. Place target on cathode.
9. Adapt the fit of the target ring by assembling with smaller spacer rings.



If target is 1/16 inch (e.g. nickel), use no spacer rings.
If target is 1/8 inch, use the 1/16" spacer ring.
If target is 3/8 inch, use the 1/8" spacer ring.
If target is 1/4 inch (e.g. copper), use both spacer rings.



10. Position target ring on target, then insert and tighten the six screws.
11. With the ohmmeter to a high resistance scale setting, check the resistance of target to ring. It should read a closed circuit (nearly **0**).
12. Adapt the cathode shield by assembling the larger spacer rings. The same size spacer rings will be needed as were used with the target ring.



13. Tighten the six screws at the base of the cathode shield.
14. With the ohmmeter, check the resistance of the target to the cathode shield. It should read an open circuit (off scale).
15. Replace platen and check turning of rotostrate.
16. Change material cards in front panel

Return to Operating Procedures for Loading substrates.